FIG. 1

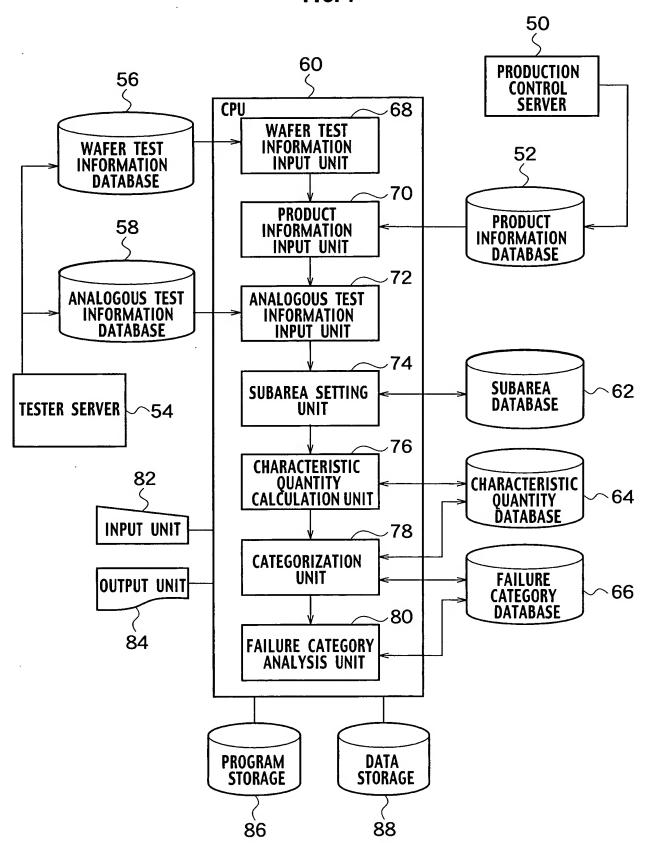


FIG. 2

PRODUCT NAME	PRODUCT	CHIP LAYOUT
PRODUCT A	MEMORY	90a 92
PRODUCT B	LOGIC	90b 94
PRODUCT C	MEMORY MERGED LOGIC	90c 96

FIG. 3

PRODUCT A	L A	PRODUCT B	T B	PRODUCT C	CI C
ELECTRIC TEST	FAILURE CODE		FAILURE CODE	ELECTRIC TEST FAILURE CODE ELECTRIC TEST FAILURE CODE	FAILURE CODE
DC	DC	POWER SHORT	PS	DC	DC
FUNCTION	75	FUNCTION	FC	AD / DA1	A1
MARGIN	MA	FREQUENCY	FQ	AD / DA2	A2
		OTHER LOGIC	10		

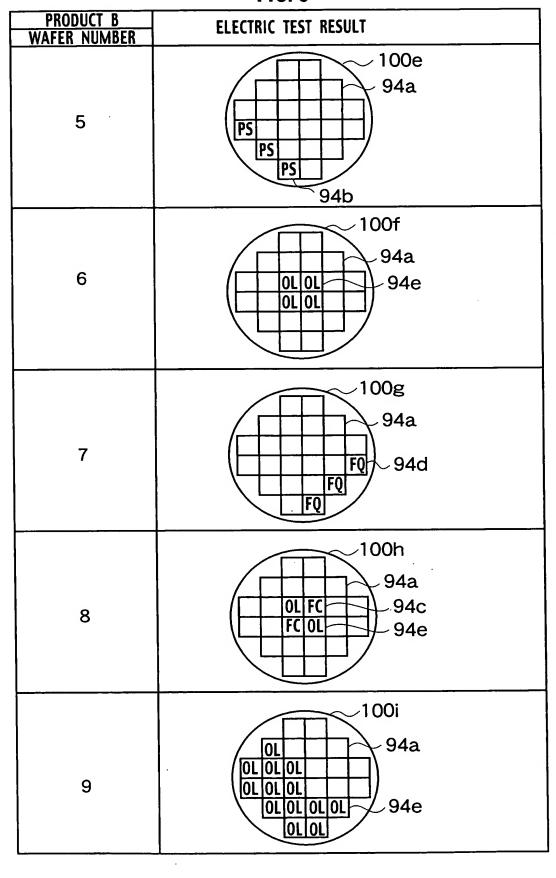
F16, 4

ANALO	ANALOGOUS ELECTRIC TEST 1	TEST 1	ANAL0	ANALOGOUS ELECTRIC TEST 2	EST 2	ANALO	ANALOGOUS ELECTRIC TEST 3	ST 3
PRODUCT	PRODUCT ELECTRIC TEST	FAILURE	PRODUCT	ELECTRIC TEST	FAILURE CODE	PRODUCT	PRODUCT ELECTRIC TEST FAILURE PRODUCT ELECTRIC TEST FAILURE CODE	FAILURE CODE
PRODUCT DC	DC	20	PRODUCT F	FUNCTION	FC	PRODUCT N	MARGIN	MA
PRODUCT	PRODUCT POWER SHORT	PS	PRODUCT B	FUNCTION	FC	PRODUCT F	FREQUENCY	FQ
PRODUCT DC	DC	20	PRODUCT C	OTHER LOGIC	10	PRODUCT A	AD / DA2	A2
			PRODUCT D	PRODUCT AD / DA1	A1			

5/21 **FIG. 5**

	11010
PRODUCT A WAFER NUMBER	ELECTRIC TEST RESULT
1	100a 92a 92b
2	100b 92a FC FC 92c
3	100c 92a 92d MA MA
4	DCDCDC DC DC 92b DC DC DC 92a DC DC DC DC DC DC DC DC

6/21 **FIG. 6**



7/21 **FIG. 7**

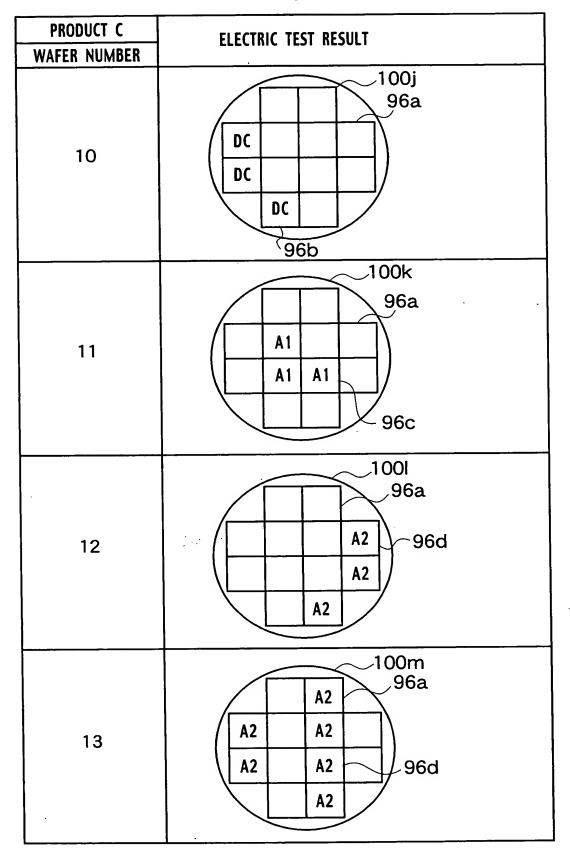


FIG. 8

DL1

DL2

DL3

DR1

DR2

DL4

DL5

FIG. 9

AREA NUMBER	SUBAREA	
1	[DR3OUTSIDE]V[DL3-DL4-DL5-DL6-DL7]	
2	[DR3OUTSIDE]V[DL7-DL8-DL1-DL2-DL3]	
3	[DR ₂ OUTSIDE] V [DL ₈ -DL ₁ -DL ₂ -DL ₃ -DL ₄]	
€		
76	[DR ₂ INSIDE] V [DL ₃ -DL ₄ -DL ₅]	
₹	₹	ж.
150	[DR1INSIDE] V [DL4-DL5-DL6-DL7-DL8]	

FIG. 10

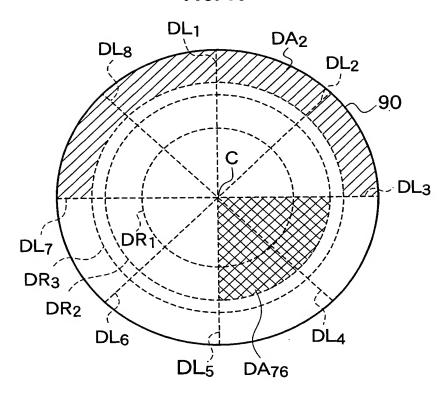


FIG. 11

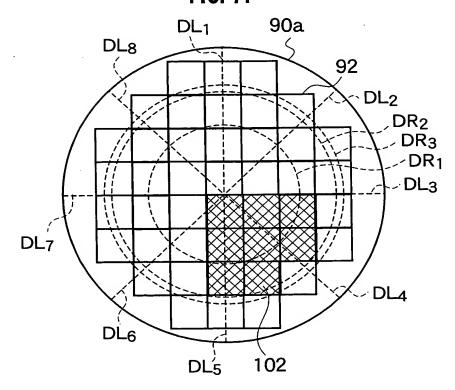


FIG. 12

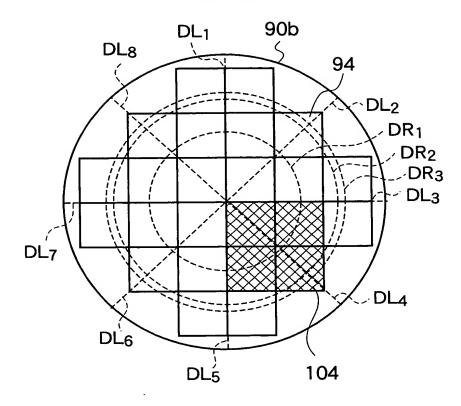


FIG. 13

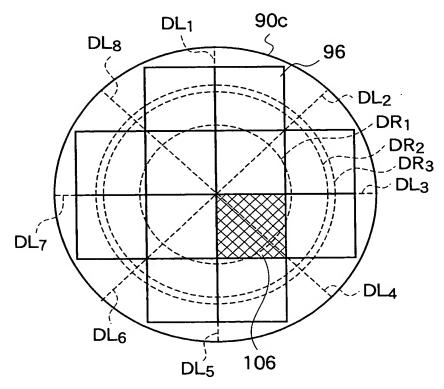


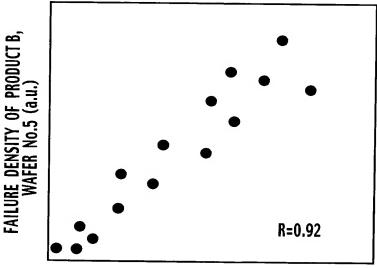
FIG. 14

PRODUCT A	1					
ELECTRIC TEST		AREA	W	AFER NUMBER		
TEST		NUMBER	1	2	3	4
		1	0.3	0	0.01	0.32
		2	0.5	0	0	0.12
DC		3	0.2	0.01	0	0.05
∳	S	î :: ×	 ?	: ×	∂ : ×	
		150	0.5	0	0	0.32
-		1	0	0.67	0	0
		2	0	0.23	0.02	0
FUNCTIO	N	3	0.01	0.15	0	0.01
∳	S	î : ×		î ×		
		150	0	0.42	0	0
		1	0	0	0.2	0.01
MARGIN		2	0	0.01	0.1	0
MARGIN		3	0	0	0.03	0
∳)	â : ¥	â : ¥	î : ¥	∱	
		150	0.02	0	0.12	0

FIG. 15

	ANALOGOUS		A , WAFER	No.1	PRODUCT B	, WAFER NO).5
	ELECTRIC TEST	ELECTRIC TEST	AREA NUMBER	FAILURE DENSITY	ELECTRIC TEST	AREA NUMBER	FAILURE DENSITY
			1	0.3	-	1	0.28
	ANALOGOUS		2	0.5		2	0.43
	ANALOGOUS ELECTRIC	DC	3	0.2	POWER SHORT	3	0.1
¥	TEST 1	FAILURE S	≈ :	÷ : ×	FAILURE ∼ ×	÷ :: ×	· »
			150	0.5		150	0.67
			1	0		1	0
	ANALOGOUG	=	2	0	FUNCTION	2	0.01
	ANALOGOUS ELECTRIC	FUNCTION FAILURE	3	0.01	FAILURE +	3	0
J	TEST 2	; ALLONE	â : ¥	÷ ; \$	OTHER LOGIC FAILURE	: ;	` ; ¥
			150	0		150	0
			1	0		1	0
ı	4334.00045		2	0		2	0.01
	ANALOGOUS ELECTRIC	MARGIN	3	0	FREQUENCY FAILURE	3	0
J	TEST 3	FAILURE			; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ;		· : *
			150	0.02		150	0

FIG. 16



FAILURE DENSITY OF PRODUCT A , WAFER No.1 (a.u.)

))		J	
·		PRODUCT	PRODUCT	PRODUCT A	PRODUCT A	PRODUCT B	Î	PRODUCT C	?	PRODUCT C
		WAFER	WAFER No.2	WAFER No.3	WAFER No.4	WAFER No.5		WAFER No.10		WAFER No.13
PRODUCT A	PRODUCT A WAFER NO.1	-	0.01	0.12	0.08	0.92		0.91		0.01
PRODUCT A	WAFER No.2	0.01	-	0.03	60.0	0.08		0.01		0.01
PRODUCT A	WAFER No.3	0.12	0.03	-	0.12	0.01	•	0.09		0.01
PRODUCT A		0.08	0.09	0.12	1	0.23		0.01		0.02
PRODUCT B	WAFER No.5	0.92	0.08	0.01	0.23	1		0.87		0.09
			•••••							·····
)		¥	
PRODUCT C	PRODUCT C WAFER No.10	0.91	0.01	0.09	0.01	0.87		1	≈ . ¥	0.07
\			•••	·					; \$}	
PRODUCT C	PRODUCT C WAFER No.13	0.01	0.01	0.01	0.02	0.09	 	0.07		
							Â		2	

F 5

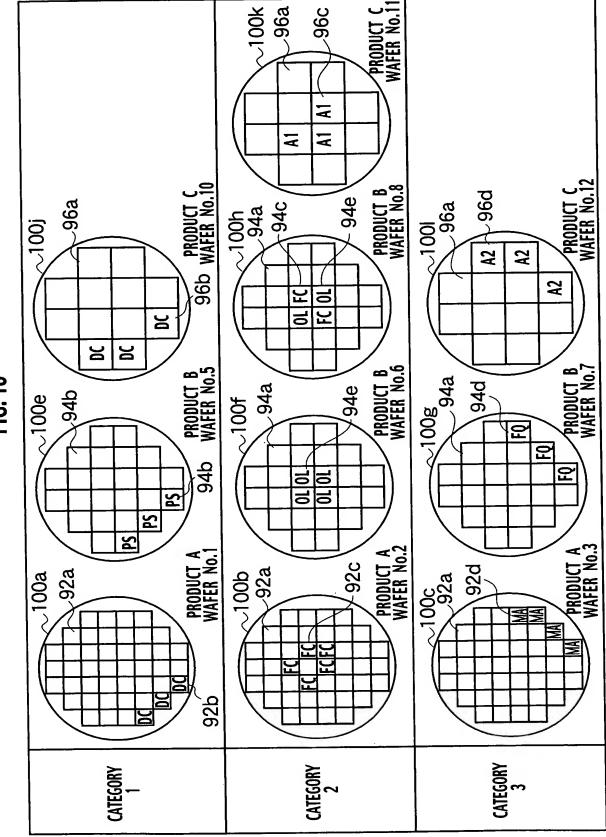
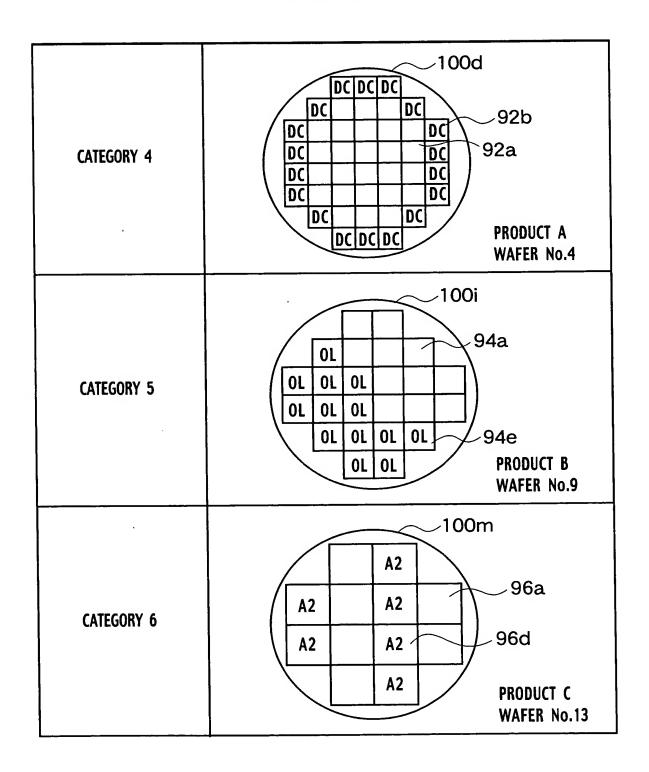
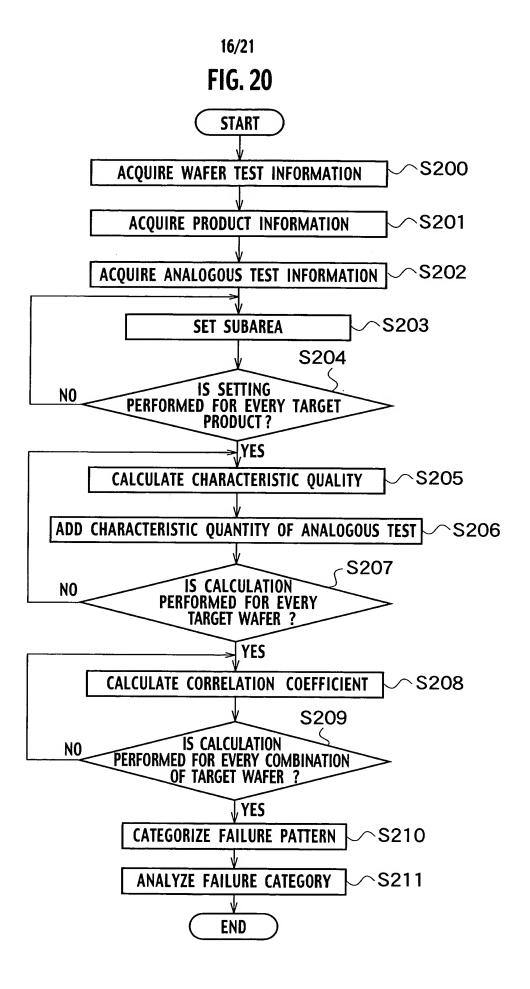


FIG. 18

FIG. 19





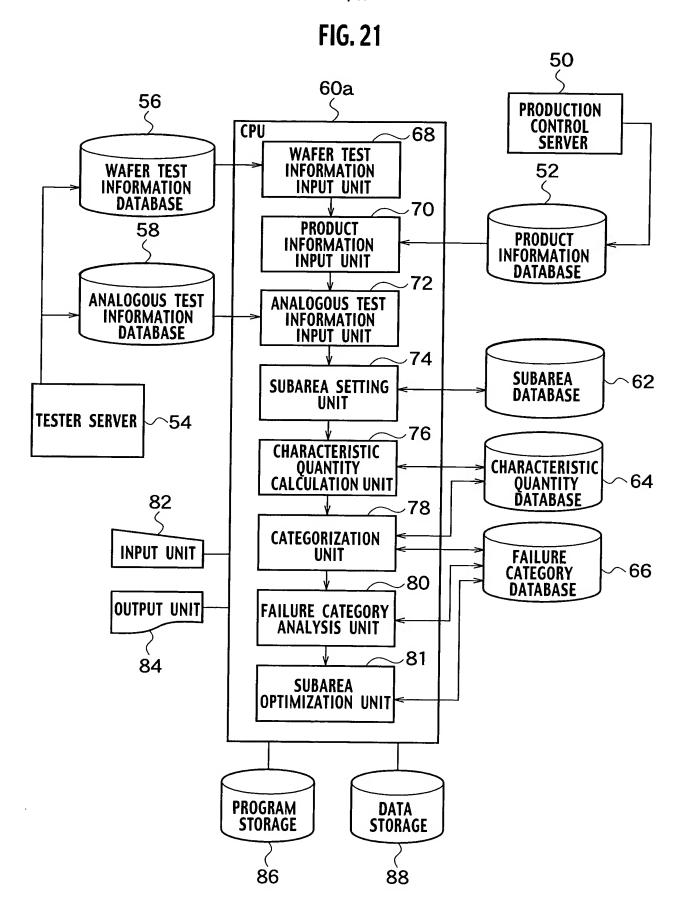


FIG. 22

	PASS / FAIL MAP	ABNORMAL PROCESS NUMBER	ABNORMAL MANUFACTURING APPRATUS	TEST STATISTIC
CATEGORY 7	94a 94c FC FC FC FC FC	136	M 1	13.6
CATEGORY 8	100o 96a 96b	96	P1	12.7

FIG. 23

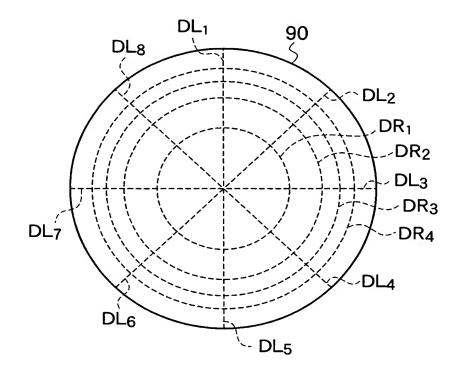


FIG. 24

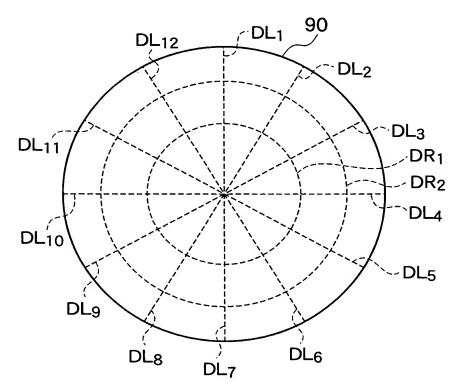


FIG. 25

	PASS / FAIL MAP	VARIATION OF TEST STATISTIC	ABNORMAL PROCESS NUMBER	ABNORMAL MANUFACTURING APPARATUS	TEST STATISTIC
CATEGORY 7	94a 100n 94c 94c FC	DI AREA DIVIDING METHOD DIVIDING CIRCLE: 2 DIVIDING LINE: 5	136	Σ	27.6
CATEGORY 8	1000 96a 96b	TEST STATISTIC D2 AREA DIVIDING METHOD D2: DIVIDING CIRCLE: 6 DIVIDING LINE: 12	82	P2	24.3

